

Glossary

Term	Definition
0603R02 (1608R05)	Chip component surface mount package. The dimensions are 0.060" by 0.030" (1.6mm by 0.8mm). R denotes Chip Resistor. 02 (05) denotes 0.020" (0.5mm) component height
AMV	Archimedes Metering Valve – Adhesive Dispense Head
BGA	Ball Grid Array
BQFP	Bumpered Quad Flat Package
Butt joint	Insertion Mount component soldered to the pc board acting as a Surface Mount component
C4	Controlled Collapse Chip Connection
CAD	Computer Aided Design
Chip component	Resistor or Capacitor with metal terminations instead of leads.
CQFP	Ceramic Quad Flat Pack
CSBGA	Chip Scale BGA
CSP	Chip Scale Package
DMRE	A "miracle" worker in the UIC Training Department
ESD	Electrostatic Discharge
FC	Flip Chip
GSM	General Surface Mount
Gull Wing	Leads spread out sideways from the component package resembling sea gull wings
HS (feeder)	High Speed
HSP	High Speed Placement
IM	Insertion Mount
IMC	IM Component
J lead	Leads bend underneath the component package resembling the letter 'J'
JEDEC	Joint Electronic Device Engineering Council
Leadless	Solder balls on the bottom of the component package (BGA) or
MCMBGA	Multichip module BGA
MELF	Metal Electrode Face Bonded
Micro Dispenser II	A type of fluxer that uses a centrifugal pump
MP (feeder)	Multi-Pitch
MQFP	Metric QFP
NCC8	Non Contact Centering Head – 4 spindle head with an early version of on the head camera
OFA	Odd-Form Assembly
OFS	Odd-Form System
Pattern	A vision algorithm that locates features other than leads (rectangles, disks, corners, cross shapes, etc.)
P2P	Part to Pad (Upward Looking Camera acronym)
PDP	Positive Displacement Pump – Adhesive Dispense Head
PEC	Pattern Error Correction
PLCC	Plastic Leaded Chip Carrier
PQFP	Plastic QFP
PTF	Platform Tray Feeder
PWC	Programmable Width Control
QFP	Quad Flat Pack
Serial Flux Head	An older style fluxer that uses a centrifugal pump

SM	Surface Mount
SMC	SM Component
SMD	SM Device
SMEMA	Surface Mount Equipment Manufacturer Association – used to designate the board handling protocol for UIC machines
SMT	SM Technology
SMTF	Stackable Matrix Tray Feeder
SOIC	Small Outline Integrated Circuit
SOJ	Small Outline ‘J’ leads
SOP	Small Outline Package
Special Leaded	A vision algorithm that locates leads of various widths by defining several groups of leads on a single side. These groups are called overlays.
SSOP	Shrink SOP
SOT	Small Outline Transistor
TAB	Tape Automated Bonding
TAPE PAKÒ	Trademark – National Semiconductor – Molded Carrier Ring
TCP	Tape Carrier Pack (component placed in TAB process)
Through-hole	Another name for IM
TFA (Rotary)	Older Thin Film Applicator
TFA (Linear)	Newer Thin Film Applicator designed specifically to assist in the assembly of flip chips
TQFP	Thin QFP
TSOP	Thin SOP
TSSOP	Thin, Shrink SOP
UFP 300+	Ultra Fine Pitch Placement Head (for fine pitch components with more than 300 leads)
UIC	Universal Instruments Corporation
UPS (software)	Universal Platform Software (OS/2 Operating System)
UPS+ (software)	Universal Platform Software (Windows 2000 Operating System)
UPS (electrical)	Uninterruptible Power Supply
USOS	Universal Supervisory Operating System
VME	Computer bus used in Universal’ s Platform and IM machines
WF	Wafer Feeder

CPU	Central processing unit
TAM	Technology Acceptance Model
PCBA	Printed Circuit Board Assembly
NPI	New Product Introduction
DFM	Design For Manufacture
MVT	Mass Verification Test
MTF	Modulation Transfer Function
ID	Industrial Design
F/T	Function Test

ERS	External Referance Spec
QRA	Quality & Reliability Assurance
DMR	Defective Material Report
RMA	Return Marerial Administration
T/C	Temperature Cycle
SPC	Statistic process Control
ISO	International Standard Organization
VMI	Visual Mechanical Inspection
FQC	Final Quality Control
EAR	Engineering Analysis Request
COGS	Cost of Goods Sold
AR	Account Payable
MIS	Management Information System
OBA	Open Box Audit
CAR	Corrective Action Request
4M	Man, Machine, Material, Method
MPS	Mass Production Schedule
WIP	Working In Process Inventrory
MI	Manual Insertion
SMD	Surface Mount Device
B/I	Burn In
ESD	Electrical Static Discharge
TAB	Tape Aotomated Bonding
TCP	Tape Carrier Package
TTL	Transister-Transister-Logic